

Peltron®

Product Name	XJS-3051β
Product Category	Conductive Adhesive
Use	Semiconductor Modules, Car Electro Devices, General Modules, Die Attach, Touch Panel, Solar Battery
Function	One Component Type, Heat Temperature Resistant, High Adhesive Strength, Good Adhesiveness at high temperature

Item	Condition	Unit	Typical Value
General Item			
Package	-	-	Pot, Syringe
Liquid Feature			
Viscosity	E type viscometer / 5rpm / @25℃	Pa·s	25
Storage stability	Unopen / Frozen (below -15℃)	-	2 months
Cured Properties			
Recommended Curing Condition	Heat air circulation oven	-	155℃ x 10 minutes
Shear Adhesive Strength @25℃	φ1mm Au cylindrical chip/ Au plated surface	N/mm ²	43
Characteristics	Moderate temperature range/short curing time (155℃x10 minutes) Very high adhesive strength to Au		

The above values are reference and not specification.



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